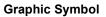
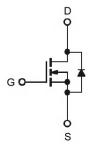


N-Channel 800-V (D-S) MOSFET

Description

The device is using advanced Super-Junction technology. This advanced technology has been especially tailored to minimize conduction loss, provide superior switching performance and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for AC/DC power conversion in switching mode operation for higher efficiency.





Features

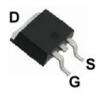
- 11A, 800V, R_{DS(ON)typ} =0.46Ω@ V_{GS} =10V
- Low Gate Charge (typical 38nC)
- High Ruggedness
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability

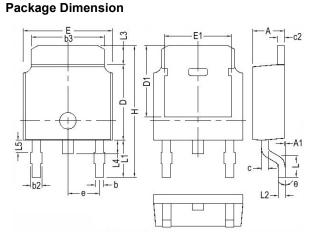
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Typical Applications

- Switching Mode Power Supply
- Adapter / Charger
- Server Power

Package type : TO-252





REF.	Millimeter		REF.	Millimeter				
	Min.	Nom.	Max.		Min.	Nom.	Max.	
Α	2.20	2.30	2.38	E1	4.40	-	-	
A1	0	-	0.127	е	2.286 BSC			
b	0.64	0.76	0.88	Н	9.40	9.40 10.00		
b2	0.77	0.84	1.14	L	1.40	1.40 1.52		
b3	5.21	5.34	5.46	L1	2.743 Ref.			
С	0.45	0.50	0.60	L2	0.508 BSC			
c2	0.45	0.50	0.58	L3	0.89	-	1.27	
D	6.00	6.10	6.223	L4	0.64	-	1.01	
D1	5.21	-	-	L5	-	-	-	
E	6.40	6.60	6.731	θ	0°	-	10°	

RoHS Compliant



N-Channel 800-V (D-S) MOSFET

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings						
Symbol	Parameter	Value	Units			
Vds	Drain-Source Voltage	800	V			
V _{GS}	Gate-Source Voltage	±30	V			
la la	Continuous Drain Current ¹ (T _c =25°C)	11	А			
lo	Continuous Drain Current ¹ (T _c =100°C)	6.7	А			
IDM	Pulsed Drain Current ^{1,2}	30	А			
las	Single Pulse Avalanche Current, L =79mH ³	2.1	А			
E _{AS}	Single Pulse Avalanche Energy, L =79mH ³	132	mJ			
dv/dt	Peak Diode Recovery dv/dt	50	V/ns			
D	Power Dissipation ⁴ (T _c =25°C)	83	W			
PD	Derating Factor Above 25°C	0.67	W/°C			
TJ/Tstg	Operating Junction and Storage Temperature	-55 to +150	°C			

Thermal Resistance Ratings					
Symbol	Parameter	Maximum	Units		
R _{0JA}	Maximum Junction-to-Ambient ¹	62.5	°C/W		
Rejc	Maximum Junction-to-Case ¹	1.5	°C/W		

Electrical Characteristics (T」=25°C unless otherwise specified)							
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units	
V _{GS (th)}	Gate Threshold Voltage	V_{DS} = V_{GS} , I_D = 250 μ A	2.5	-	4.5	V	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250µA	800	-	-	V	
BV _{DSS} / ΔTJ	Breakdown Voltage Temperature Coefficient	I_D = 250µA, referenced to 25°C	-	0.6	-	V/°C	
Igss	Gate-Source Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 30V$	-	-	±100	nA	
IDSS	Drain-Source Leakage Current	V _{DS} =800V, V _{GS} =0V, T _C =25°C V _{DS} =640V, V _{GS} =0V, T _C =125°C	-	-	1 10	μA	
RDS (on)	Static Drain-Source On-Resistance	V_{GS} =10V, I_{D} =5.5A	-	0.46	0.5	Ω	



N-Channel 800-V (D-S) MOSFET

Dynamic						
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Qg	Total Gate Charge ²	V _{DS} =640V		38		
Qgs	Gate-Source Charge	I _D =11A		4		nC
Q _{gd}	Gate-Drain Charge	V _{GS} =10V		4.4		
td(on)	Turn-On Delay Time ²	V _{DS} =400V		26		
tr	Rise Time	I _D =5.5A		60		
td(off)	Turn-Off Delay Time	V _{GS} =10V		75		ns
tf	Fall Time	R _G =25Ω		44		
Ciss	Input Capacitance	V _{DS} =100V		680		
Coss	Output Capacitance	V _{GS} =0V		140		pF
CRSS	Reverse Transfer Capacitance	f=1.0MHz		5		

Source-Drain Diode							
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units	
ls	Continuous Source Current ^{1,5}		-	-	11		
Ism	Pulsed Source Current ^{2,5}	$V_{\rm G} = V_{\rm D} = 0$ V, Force Current	-	-	30	A	
Vsd	Diode Forward Voltage ²	Is=11A, V _{GS} =0V, T _J =25°C	-	-	1.5	V	
trr	Reverse Recovery Time ²	Is =11A, V _{GS} =0V, dI _F / dt =		270		ns	
Qrr	Reverse Recovery Charge ²	100A/µs		3.3		μC	

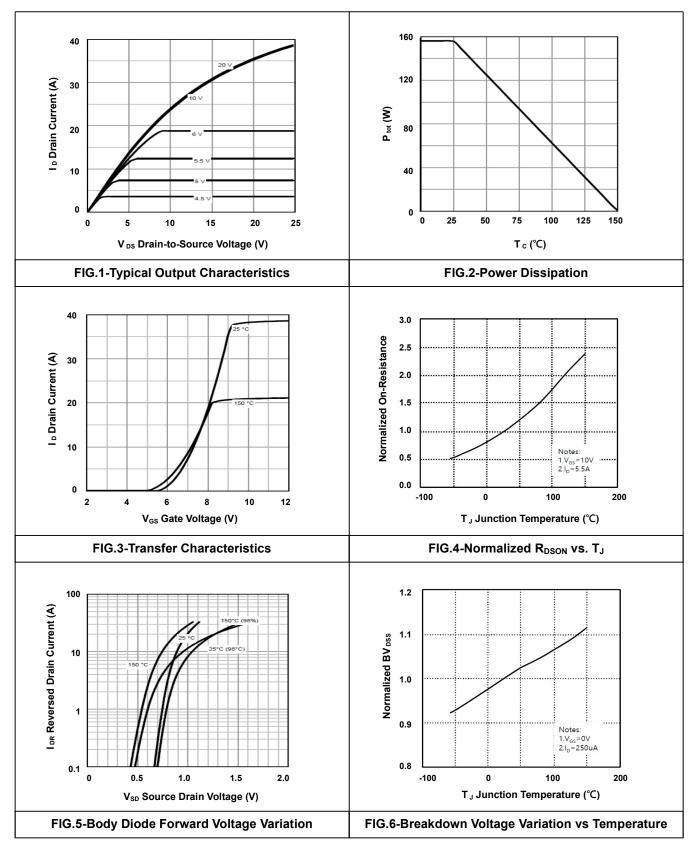
Notes

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2. The data tested by pulsed, pulse width \leq 300us, duty cycle \leq 2%.
- 3. The EAS data shows maximum rating. The test condition is V_{DD} =100V, L=79mH, I_{AS}=2.4A.
- 4. The power dissipation is limited by 150 $^\circ\!\mathrm{C}$ junction temperature.
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



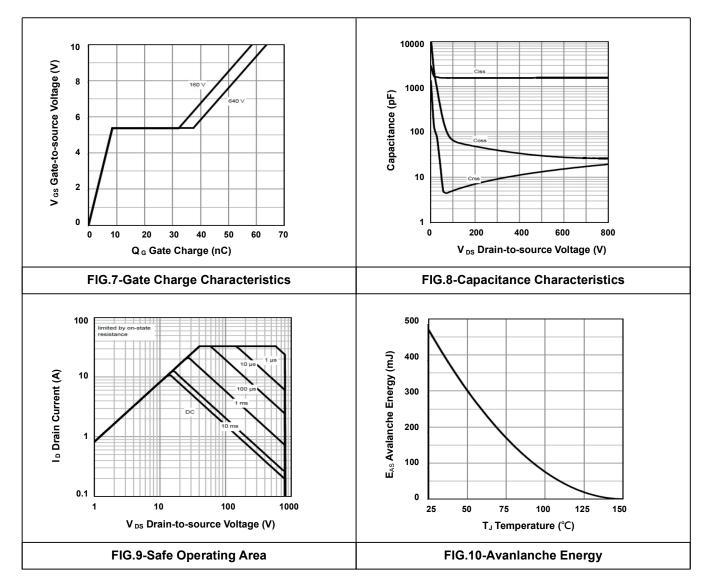
N-Channel 800-V (D-S) MOSFET

• Typical Electrical Characteristics





N-Channel 800-V (D-S) MOSFET





N-Channel 800-V (D-S) MOSFET

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